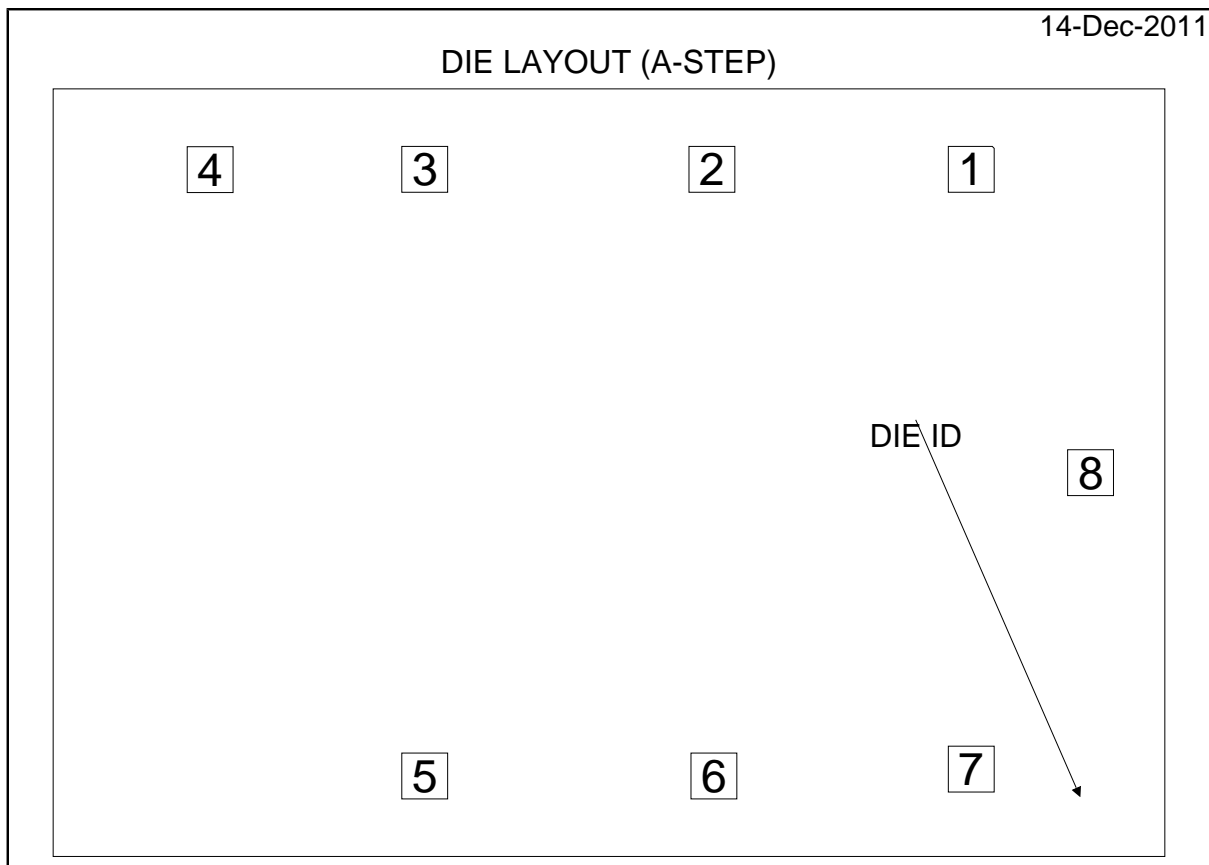


LMP2012 MDE MCD5060A
Dual, High Precision, Rail-to-Rail Output Operational Amplifier



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMV2012A	Bond Pad Opening Size (min)	88.00µm x 88.00µm
Die Step	A	Bond Pad Metalization	AL1.0%SI0.5%CU
Physical Attributes		Passivation	PECVDON NITRIDE
Wafer Diameter	152.4mm	Back Side Metal	BAREBACK
Die Size (Drawn)	2133.6µm x 1473.2µm 84.0mils x 58.0mils	Back Side Connection	Floating or GND
Thickness	304.8µm Nominal		
Min Pitch	493.92µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
OUT A	1	695.28	582.16	88.00	x	88.00
IN A -	2	197.52	582.16	88.00	x	88.00
IN A +	3	-353.68	582.16	88.00	x	88.00
V -	4	-765.52	581.60	88.00	x	88.00
IN B +	5	-353.68	-582.16	88.00	x	88.00
IN B -	6	201.36	-582.16	88.00	x	88.00
OUT B	7	695.28	-568.96	88.00	x	88.00
V +	8	924.24	0.00	88.00	x	88.00

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